

MACDERMID ALPHA TO PRESENT ADVANTAGES OF SOLDER PASTE IN SHINGLING INTERCONNECTION AT SNEC PV POWER EXPO IN SHANGHAI CHINA

(Waterbury, CT USA) – July 31, 2020 - The Assembly Division of MacDermid Alpha Electronics Solutions, a world leader in the production of electronics soldering and bonding materials, will be presenting a technical paper on the “*Advantages of Solder Paste in Shingling Interconnection*” during the SNEC 14th (2020) International Photovoltaic (PV) Power Generation and Smart Energy Exhibition & Conference taking place from August 7-10 in Shanghai, China.

The paper, “*Advantages of Solder Paste in Shingling Interconnection*” will focus on the use of solder paste in novel PV assembly techniques such as shingling and will be presented by Narahari Pujari, Global Technology Manager - PV, MacDermid Alpha.

“Shingling interconnection allows an increase of module power output without introducing substantial modification in the cell or assembly process. Conventionally, the interconnection in shingling is achieved by ECA (electrically conductive adhesive) gluing. However, long term outdoor performance data proving their stability against environmental influences has produced mixed results. Further, cost of the ECA is a big limiting factor in the price sensitive PV market,” comments Narahari Pujari. “Solder paste is a natural choice in any interconnection technology, including PV as it has a proven record in the semiconductor industry and is much more cost effective.”

He continues, “In this work, we investigated the application of solder pastes in shingle cell interconnection. Our findings confirm that solder paste can be used in this technology as a joining material and can produce the required strength and reliability as per IEC61215 which is standard for accelerated aging tests”.

Pujari’s presentation will give further insights of various solder pastes that can be used in shingling as well as other advanced PV interconnection technologies.

For more information on Alpha’s solutions for [Photovoltaic](#) applications, please visit MacDermidAlpha.com

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2020 SNEC PV Power Expo
Date: 7th August, 2020 – 10th August 2020
Venue: Kerry Hotel Pudong Shanghai, China

Presentation: Advantages of solder paste in shingling interconnection
Date: 8th August 2020
Time: 14.00-17.00
Presented by: Narahari Pujari, Global technology Manager – PV, MacDermid Alpha Electronics Solutions